	1 A A A A A A A A A A A A A A A A A A A
ΡΛΝ	JIT
	SEMI
	CONDUCTOR

### **60V N-Channel Enhancement Mode MOSFET**

Voltage

Current 33 A

#### Features

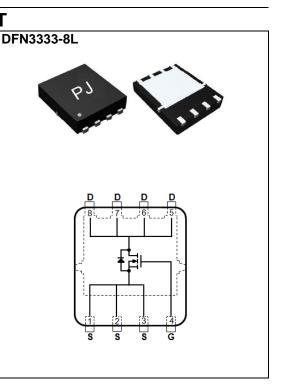
- $R_{DS(ON)}$ ,  $V_{GS}@10V$ ,  $I_D@16A < 17m\Omega$
- R<sub>DS(ON)</sub>, V<sub>GS</sub>@4.5V, I<sub>D</sub>@8A<20mΩ
- Advanced Trench Process Technology

60 V

- High density cell design for ultra low on-resistance
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

#### **Mechanical Data**

- Case : DFN3333-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.001 ounces, 0.03 grams



#### **Maximum Ratings and Thermal Characteristics** (T<sub>A</sub>=25<sup>o</sup>C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V <sub>DS</sub>	60		
Gate-Source Voltage		$V_{GS}$	<u>+</u> 20	V	
Continuous Drain Current <sup>(Note 4)</sup>	Tc=25°C		33		
	T <sub>C</sub> =100°C	ID	21	А	
Pulsed Drain Current(Note 1)	Tc=25°C	I <sub>DM</sub>	132		
Power Dissipation	T <sub>C</sub> =25°C	6	48	10/	
	Tc=100°C	Po	24	W	
Continuous Drain Current <sup>(Note 4)</sup>	T <sub>A</sub> =25°C		7.3		
	T <sub>A</sub> =70°C	lo	5.9	A	
Power Dissipation	T <sub>A</sub> =25°C	6	2.4		
	T <sub>A</sub> =70°C	Po	1.6	W	
Single Pulse Avalanche Energy <sup>(Note 6)</sup>		E <sub>AS</sub>	45	mJ	
Operating Junction and Storage Temperature Range		TJ,TSTG	-55~175	°C	
Typical Thermal Resistance <sup>(Note 4,5)</sup>	Junction to Case	R <sub>θJC</sub>	3.1		
	Junction to Ambient	R <sub>0JA</sub>	62.5	°C/W	



#### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

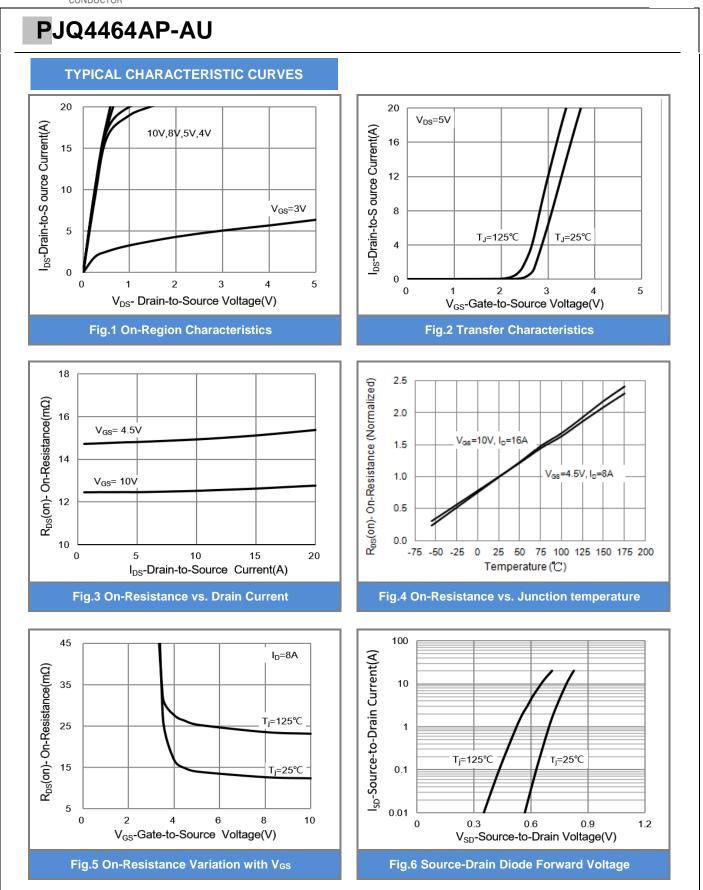
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	-	-	Ň
Gate Threshold Voltage	V <sub>GS(th)</sub>	Vds=Vgs, Id=250uA	1	1.7	2.5	V
Drain-Source On-State Resistance	_	Vgs=10V, Id=16A	-	13	17	mΩ
	RDS(on)	V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A	-	16	20	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Source Leakage Current	lgss	V <sub>GS</sub> = <u>+</u> 20V, V <sub>DS</sub> =0V	-	-	<u>+</u> 100	nA
Dynamic <sup>(Note 5)</sup>						
Total Gate Charge	Qg	$V_{DS}=30V, I_{D}=10A,$ $V_{GS}=4.5V^{(Note 2,3)}$	-	13.5	-	
Gate-Source Charge	Q <sub>gs</sub>		-	4.8	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	4.9	-	
Input Capacitance	Ciss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHZ	-	1574	-	
Output Capacitance	Coss		-	118	-	pF
Reverse Transfer Capacitance	Crss		-	77	-	
Turn-On Delay Time	td <sub>(on)</sub>		-	11	-	
Turn-On Rise Time	tr	V <sub>DD</sub> =15V, I <sub>D</sub> =1A,	-	11	-	
Turn-Off Delay Time	td <sub>(off)</sub>	$V_{GS}=10V, R_G=6\Omega$ (Note 2,3)	-	35	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	8.1	-	
Drain-Source Diode	·	·				
Maximum Continuous Drain-Source Diode Forward Current	Is		-	-	33	А
Reverse Recovery Time	V <sub>SD</sub>	Is=1A, V <sub>GS</sub> =0V	-	0.68	1	V

NOTES :

- 1. Pulse width
- 2. Essentially independent of operating temperature typical characteristics.
- Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub> =25°C.
- 4. The maximum current rating is package limited.
- 5.  $R_{\Theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
- 6. The test condition is L=0.1mH,  $I_{AS}$ =30A,  $V_{DD}$ =25V,  $V_{GS}$ =10V, Starting  $T_J$ =25°C.
- 7. Guaranteed by design, not subject to production testing.

January 27,2022

PJQ4464AP-AU-REV.01

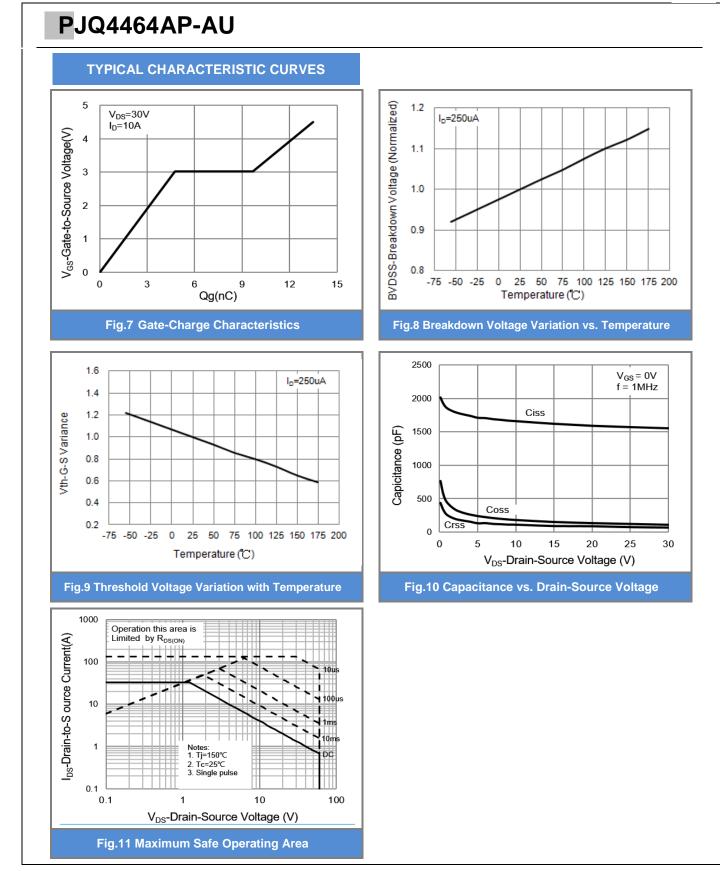




January 27,2022

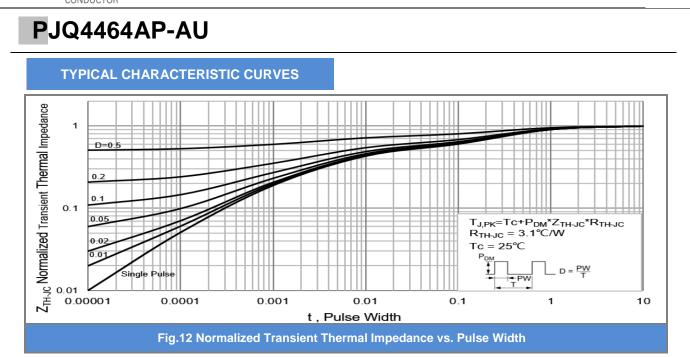
PJQ4464AP-AU-REV.01

#### Page 4





Page	5

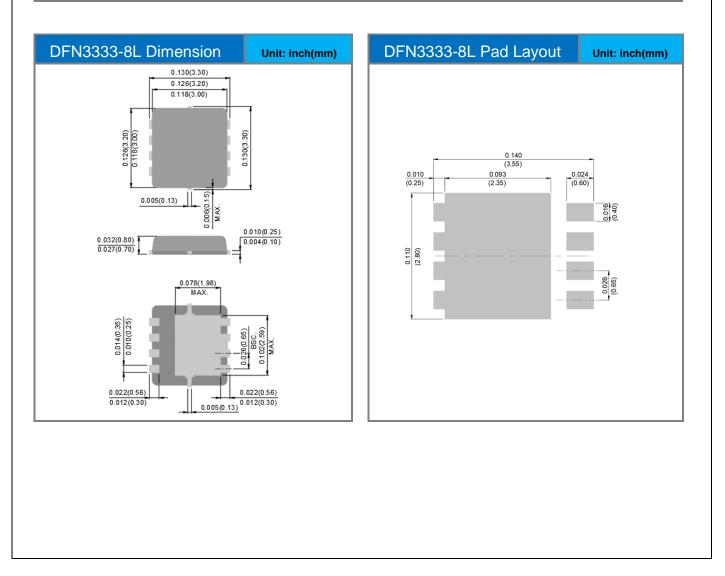




### Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking	Version
PJQ4464AP-AU_R2_000A1	DFN3333-8L	5K pcs / 13" reel	4464	Halogen free RoHS compliant

### **Packaging Information & Mounting Pad Layout**





### Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from Panjit International Inc..
- Panjit International Inc. reserves the rights to make changes of the content herein the document anytime without notification. Please refer to our website for the latest document.
- Panjit International Inc. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- Panjit International Inc. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. Panjit International Inc. makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- The products shown herein are not designed and authorized for equipments relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panjit International Inc. for any damages resulting from such improper use or sale.
- Since Panjit uses lot number as the tracking base, please provide the lot number for tracking when complaining.